

Abstract

Two molds (102, 104) are provided formed of semiconductor material. The molds (102, 104) have substantially planar working faces (108, 110) into which recesses (106, 112) are formed. In use the molds (102, 104) are pressed together with the working faces (108, 110) opposed so the recesses (106, 112) form mold cavities. The molds (102, 104) only contact each other in the plane of the working faces (108, 110)

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